

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4178021

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ADD ACCIDENTALLY OMITTED SIXTH INVENTOR previously recorded on Reel 031931 Frame 0584. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNOR'S INTEREST.
CONVEYING PARTY DATA	
Name	Execution Date
CHEN-HUA YU	12/26/2013
TZU-SHIUN SHEU	12/26/2013
SHIN-PUU JENG	12/27/2013
SHIH-PENG TAI	12/26/2013
AN-JHIH SU	12/26/2013
CHI-HSI WU	12/27/2013
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14132709
CORRESPONDENCE DATA	
Fax Number:	(972)732-9218
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	972-732-1001
Email:	docketing@slatermatsil.com
Correspondent Name:	SLATER MATSIL, LLP
Address Line 1:	17950 PRESTON RD., SUITE 1000
Address Line 4:	DALLAS, TEXAS 75252
ATTORNEY DOCKET NUMBER:	TSM13-1309
NAME OF SUBMITTER:	MARANDA BRALLEY
SIGNATURE:	/Maranda Bralley/

DATE SIGNED:	12/09/2016
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 8 source=TSM13-1309 Assignment as filed#page1.tif source=TSM13-1309 Assignment as filed#page2.tif source=TSM13-1309 Assignment as filed#page3.tif source=TSM13-1309 Assignment as filed#page4.tif source=TSM13-1309 Assignment as filed#page5.tif source=TSM13-1309 Assignment as filed#page6.tif source=TSMP13-1309 Assignment NEW#page1.tif source=TSMP13-1309 Assignment NEW#page2.tif	

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>CHEN-HUA YU</td><td>12/26/2013</td></tr><tr><td>TZU-SHIUN SHEU</td><td>12/26/2013</td></tr><tr><td>SHIN-PUU JENG</td><td>12/27/2013</td></tr><tr><td>SHIH-PENG TAI</td><td>12/26/2013</td></tr><tr><td>AN-JHIH SU</td><td>12/26/2013</td></tr></tbody></table>	Name	Execution Date	CHEN-HUA YU	12/26/2013	TZU-SHIUN SHEU	12/26/2013	SHIN-PUU JENG	12/27/2013	SHIH-PENG TAI	12/26/2013	AN-JHIH SU	12/26/2013	
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RECEIVING PARTY DATA													
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.												
Street Address:	NO. 8, LI-HSIN RD. 6												
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK												
City:	HSIN-CHU												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number:	(972)732-9218												
Phone:	972-732-1001												
Email:	docketing@slater-matsil.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	SLATER & MATSIL, L.L.P.												
Address Line 1:	17950 PRESTON ROAD, SUITE 1000												
Address Line 4:	DALLAS, TEXAS 75252												

PATENT

ATTORNEY DOCKET NUMBER:	TSM13-1309
NAME OF SUBMITTER:	WENDY SAXBY
Signature:	/Wendy Saxby/
Date:	01/09/2014
Total Attachments: 2 source=43Y1837#page1.tif source=43Y1837#page2.tif	
RECEIPT INFORMATION	
EPAS ID:	PAT2674903
Receipt Date:	01/09/2014

PATENT

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

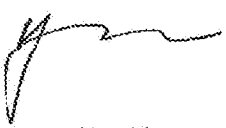
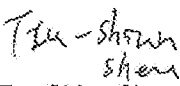


WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77, Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Chip-on-Substrate Packaging on Carrier			
SIGNATURE OF INVENTOR AND NAME	 Chen-Hua Yu	 Tzu-Shiun Sheu	 Shin-Puu Jeng	 Shih-Peng Tai
DATE	12/26/13	12/26/2013	12/27/2013	2013/12/26
RESIDENCE	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan	Xinpu Township, Taiwan

ATTORNEY DOCKET NO.
TSM13-1309

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of , with its principal office at No. 8, Li-Hsin Rd. 8 Science-Based Industrial Park, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

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SIGNATURE OF INVENTOR AND NAME	An-Jhih Su	Chi-Hsi Wu		
DATE	12/26/2013	12/27/2013		
RESIDENCE	Bade City, Taiwan	Hsin-Chu, Taiwan		

ASSIGNMENT

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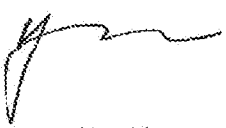
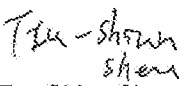


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DATE	12/26/2013	12/27/2013		
RESIDENCE	Bade City, Taiwan	Hsin-Chu, Taiwan		